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Press Release



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Pretech AT teams up with Synova: first automatized Laser-Microjet- dicing/scribing and edge grinding system for wafers ready for commercialization

Synova SA and Pretech AT form a partnership to build an automated wafer dicing, scribing and edge grinding system. Pretech AT is a privately owned company specialized in automatic handling and cleaning of wafers for the semiconductor, LED and PV markets. Pretech's expertise combined with Synova's Laser Dicing System LDS300 delivers a production tool capable of handling wafers of tapeframes. The wafers or wafer frames are transferred to the working chuck, processed with the Laser MicroJet technology, then transferred to the cleaning station and subsequently stored in cassettes of 13 or 25 wafers.

The strong demand for the automatic dicing and grinding system has enabled Pretech AT to obtain government funding in order to cooperate in the development with Synova. A first machine is currently commissioned and alpha testing is available to select customers in Japan. The advantage of the LMJ over the conventional edge grinding and dicing processes is the reduced mechanical stress and cracking. This stress free process leads to yield improvement –in subsequent production processes. There is a continued interest to improve yields by numerous wafer suppliers as well as semiconductor backend of the line (BEOL).

Due to the modular design of both systems from Synova and Pretech AT, the integration will be executed rapidly enabling a full commercial launch in the fourth quarter of 2011. Both parties are confident that the combination of Synova's Laser Microjet® Technology with Pretech AT's fully automated handling system will meet the stringent demands of the semiconductor supply chain, leading to new business and market opportunities.

Pre-Tech is a private company that was founded in 1982 and is located in Japan. Pre-Tech specializes in developing and manufacturing of automation capable of removing sub-micron particles in Semiconductor, LED, and PV markets. Pretech AT also specialized in automatic handling and cleaning of wafers.

Since 1997, Synova SA, has been pioneering the Laser MicroJet technology by exploiting the synergy of laser power with water. The water-guided laser beam cuts/drills parallel and cleans kerfs/holes with virtually no heat impact. The technology enables unprecedented possibilities and allows for substantial reduction of total cost in various high-precision application fields.

Synova Laser Technology

Where others see impossibilities, we see solutions